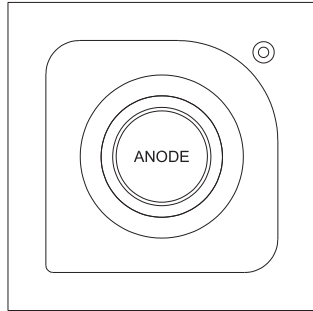


# CPD102X-CMPD6263

## Schottky Diode Die

### 15 mA, 70 Volt

The CPD102X-CMPD6263 is a silicon epitaxial planar Schottky diode designed for switching applications requiring low forward voltage drop.



BACKSIDE CATHODE R0

#### MECHANICAL SPECIFICATIONS:

Die Size	9.0 x 9.0 MILS
Die Thickness	5.9 MILS
Anode Bonding Pad Size	4.8 MILS DIAMETER
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 9,000Å
Scribe Alley Width	2.4 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	210,600

#### MAXIMUM RATINGS: ( $T_A=25^\circ\text{C}$ )

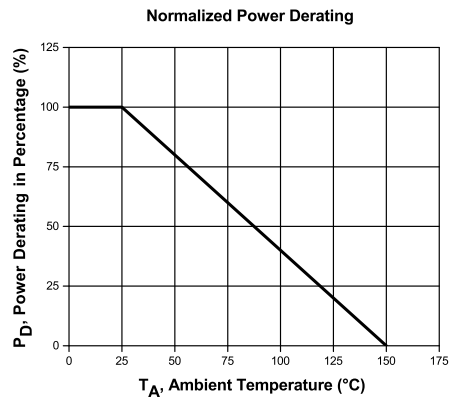
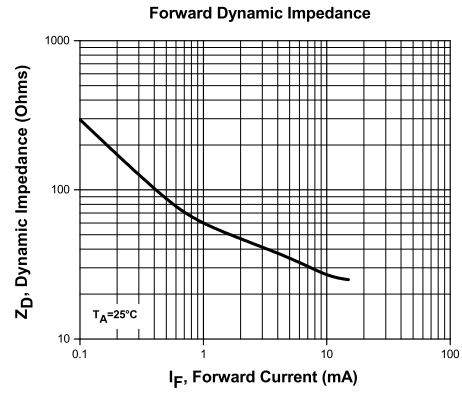
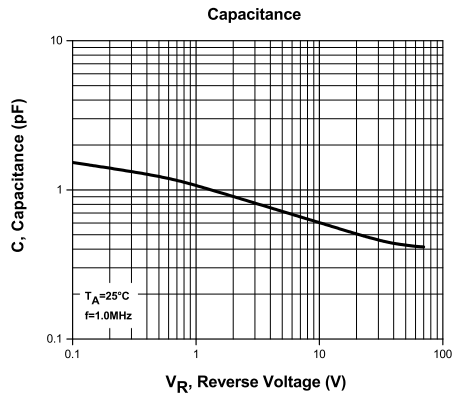
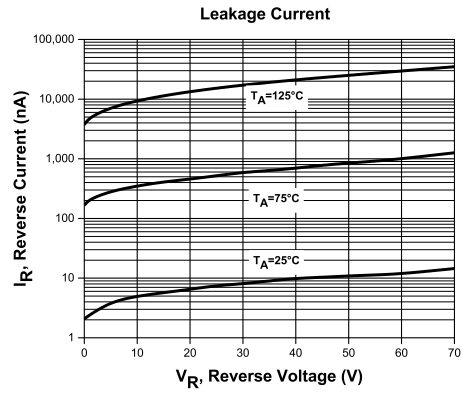
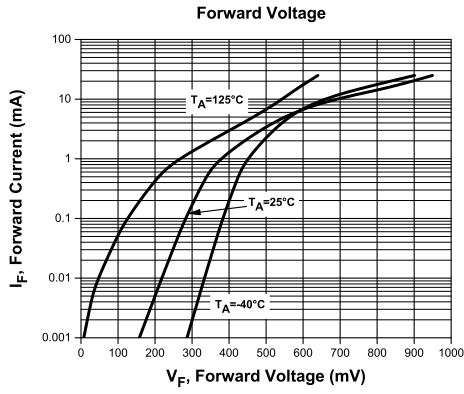
	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	$V_{RRM}$	70	V
Continuous Forward Current	$I_F$	15	mA
Peak Forward Surge Current, $t_p=1.0\text{s}$	$I_{FSM}$	50	mA
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

#### ELECTRICAL CHARACTERISTICS: ( $T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
$I_R$	$V_R=50\text{V}$		10	200	nA
$BV_R$	$I_R=10\mu\text{A}$	70			V
$V_F$	$I_F=1.0\text{mA}$		395	410	mV
$C_J$	$V_R=0, f=1.0\text{MHz}$			2.0	pF

# CPD102X-CMPD6263

## Typical Electrical Characteristics



## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

**CT:** Singulated die in tray (waffle) pack.  
(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: CP211-PART NUMBER-CM)

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### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: CP211-PART NUMBER-WN)

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### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:  
[www.centrasemi.com/bdspecs](http://www.centrasemi.com/bdspecs)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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[www.centrasemi.com](http://www.centrasemi.com)

**Worldwide Field Representatives:**  
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**Worldwide Distributors:**  
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